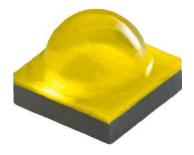
Cree® XLamp® XB-D LEDs



PRODUCT DESCRIPTION

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The XLamp[®] XB-D LED brings next-generation performance, price and size to all LED lighting applications. The XB-D's footprint enables smaller designs with densely packed arrays for better light mixing and concentration.

The XB-D shares common footprint and uniform package design across all white and color configurations, simplifying board and optical designs for many LED systems. The XB-D is optimized to dramatically lower system cost in any illumination application, from indoor and outdoor lighting to architectural and transportation lighting.



FEATURES

- Cree's smallest lighting class LED: 2.45 X 2.45 mm
- XB-D white binned @ 85 °C; XB-D color binned @ 25 °C
- Up to 136 lm/W in cool white (@ 85 °C, 350 mA)
- Available in white, 80-minimum CRI white, and 70-minimum CRI cool white, royal blue, blue, green, amber, red-orange & red
- 1 A maximum drive current
- Wide viewing angle: from 115° (white) to 140° (red)
- Reflow solderable JEDEC
 J-STD-020C compatible
- Unlimited floor life at ≤ 30 °C/85% RH
- Electrically neutral thermal path
- RoHS and REACh compliant
- UL[®] recognized component (E349212)



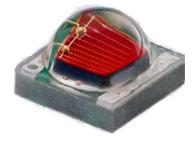


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CHARACTERISTICS

Characteristics	Unit	Minimum	Typical	Maximum
Thermal resistance, junction to solder point - white, royal blue, blue	°C/W		6.5	
Thermal resistance, junction to solder point - green	°C/W		11	
Thermal resistance, junction to solder point - amber	°C/W		7	
Thermal resistance, junction to solder point - red-orange, red	°C/W		5	
Viewing angle (FWHM) - white	degrees		115	
Viewing angle (FWHM) - royal blue, blue, green	degrees		135	
Viewing angle (FWHM) - amber, red-orange, red	degrees		140	
Temperature coefficient of voltage - white	mV/°C		-2.5	
Temperature coefficient of voltage - royal blue, blue, green	mV/°C		-3.3	
Temperature coefficient of voltage - amber, red-orange, red	mV/°C		-2	
ESD withstand voltage (HBM per Mil-Std-883D) - white, royal blue, blue, green	V			8000
ESD classification (HBM per Mil-Std-883D) - amber, red-orange, red			Class 2	
DC forward current	mA			1000
Reverse voltage	V			-5
Forward voltage (@ 350 mA, 85 °C) - white	V		2.9	3.5
Forward voltage (@ 350 mA, 25 °C) - royal blue, blue	V		3.1	3.7
Forward voltage (@ 350 mA, 25 °C) - green	V		3.3	3.9
Forward voltage (@ 350 mA, 25 °C) - amber, red-orange, red	V		2.25	2.6
LED junction temperature	°C			150

FLUX CHARACTERISTICS - WHITE (T₁ = 85 °C)

The following table provides several base order codes for XLamp XB-D LEDs. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XLamp XB-D LED Binning and Labeling document.

Color	сст	Range	Mini	mum Luminous @ 350 mA	Flux		d Minimum Flux (lm)**	Order Code								
Color	Minimum	Maximum	Group	Flux (lm) @ 85 °C	Flux (lm) @ 25 °C*	700 mA	1000 mA	Order Code								
Cool White	5000 K	8300 K	R3	122	139	210	271	XBDAWT-00-0000-000000F51								
Cool white	5000 K	8300 K	R2	114	130	196	253	XBDAWT-00-0000-000000E51								
70 CRI Minimum	5000 K	8300 K	R3	122	139	210	271	XBDAWT-00-0000-00000BF51								
Cool White	5000 K	5000 K	8300 K	R2	114	130	196	253	XBDAWT-00-0000-00000BE51							
											R2	114	130	196	253	XBDAWT-00-0000-00000LEE4
Neutral White	3700 K	5000 K	Q5	107	122	184	237	XBDAWT-00-0000-00000LDE4								
			Q4	100	114	172	222	XBDAWT-00-0000-00000LCE4								
			Q4	100	114	172	222	XBDAWT-00-0000-00000HCE7								
80 CRI Minimum White	2600 K	2600 K	6200 K	Q3	93.9	107	162	208	XBDAWT-00-0000-00000HBE7							
			Q2	87.4	100	150	194	XBDAWT-00-0000-00000HAE7								
		K 3700 K	Q4	100	114	172	222	XBDAWT-00-0000-00000LCE7								
Warm White	2600 K		Q3	93.9	107	162	208	XBDAWT-00-0000-00000LBE7								
			Q2	87.4	100	150	194	XBDAWT-00-0000-00000LAE7								

Notes:

- Typical CRI for Neutral White, 3700 K 5000K CCT is 75.
- Typical CRI for Warm White, 2600 K 3700 K CCT is 80.
- Minimum CRI for 70 CRI Minimum Cool White is 70.
- Minimum CRI for 80 CRI Minimum White is 80.
- * Flux values @ 25 °C are calculated and are for reference only.
- ** Calculated flux values at 700 mA and 1000 mA are for 85 °C and are for reference only.

Cree maintains a tolerance of ±7% on flux and power measurements, ±0.005 on chromaticity (CCx, CCy) measurements and ±2 on CRI measurements. See the Measurements section (page 14).

FLUX CHARACTERISTICS - COLOR (T_J = 25 °C)

The following tables provide several base order codes for XLamp XB-D LEDs. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XLamp XB-D LED Binning and Labeling document.

	Do	minant Wav	ninant Wavelength Range			n Radiant Flux											
Color	Minimum		Maximum		(mW) @ 350 mA		Order Code										
	Group	DWL (nm)	Group	DWL (nm)	Group	Flux (mW)											
										34 (N)	550	XBDROY-00-0000-000000N01					
								33 (M)	525	XBDROY-00-0000-000000M01							
Royal Blue	D36	450	D57	D57	D57	D57	D57	D57	D57	D57	465	57 465	465	32 (L)	500	XBDROY-00-0000-000000L01	
				31 (K)	475	XBDROY-00-0000-000000K01											
															30 (J)	450	XBDROY-00-0000-000000J01

	Do	minant Wav	elength Rar	nge	Minimum	Luminous Flux											
Color	Minimum		Maximum		(lm) @ 350 mA		(lm) @ 350 mA		Order Code								
	Group	DWL (nm)	Group	DWL (nm)	Group	Flux (lm)											
			B6		M2	39.8	XBDBLU-00-0000-000000201										
Blue	B3	465		B6	B6	B6 48	B6	B6 48	B6	B6	B6	B6	B6 485	485	К3	35.2	XBDBLU-00-0000-000000Z01
								K2	30.6	XBDBLU-00-0000-000000Y01							

	Do	minant Wav	elength Ra	ıge	Minimum Luminous Flux								
Color	Minimum		Maximum		(lm) @ 350 mA		Order Code						
	Group	DWL (nm)	Group	DWL (nm)	Group	Flux (lm)							
							Q5	107	XBDGRN-00-0000-000000D01				
Green	G2	520	G4	E2E	525	525	535	535	535	535	Q4	100	XBDGRN-00-0000-000000C01
Green	en GZ 520 G4	G4	520 64	64	64	64	64				Q3	93.9	XBDGRN-00-0000-000000B01
													Q2

	Do	minant Wav	elength Rar	nge	Minimum Luminous Flux											
Color	Minimum		Maximum		(lm) @ 350 mA		Order Code									
	Group	DWL (nm)	Group	DWL (nm)	Group	Flux (lm)										
														P3	73.9	XBDAMB-00-0000-000000801
Amber	40	FOF	A3 595	A3	A3	A3	FOF	A3 595	595	P2	67.2	XBDAMB-00-0000-000000701				
Amber	nber A2 585 A	A3 5					A3			N4	62	XBDAMB-00-0000-000000601				
				N3	56.8	XBDAMB-00-0000-000000501										



	Dominant Wavelength Range				Minimum	Luminous Flux	Order Code						
Color	Minimum		Maximum		(lm) @ 350 mA								
	Group	DWL (nm)	Group	DWL (nm)	Group	Flux (lm)							
			04	04	04						Q4	100	XBDRDO-00-0000-000000C01
							Q3	93.9	XBDRDO-00-0000-000000B01				
Red- Orange	03	610				04	04	04	04 620	04	04 620	Q2	87.4
				P4	80.6	XBDRDO-00-0000-000000901							
						P3	73.9	XBDRDO-00-0000-000000801					

FLUX CHARACTERISTICS - COLOR (T_J = 25 °C) - CONTINUED

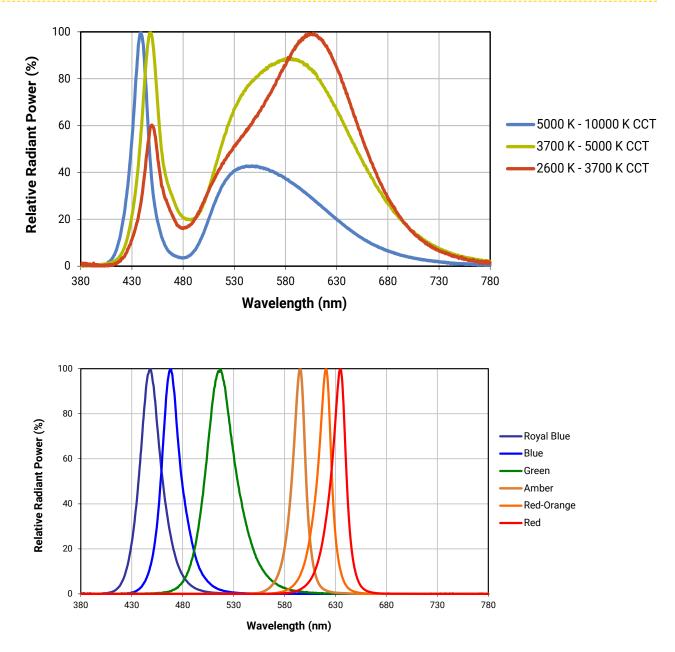
	Do	minant Wav	elength Rar	ige	Minimum	Luminous Flux										
Color	Mini	Minimum		Maximum		@ 350 mA	Order Code									
	Group	DWL (nm)	Group	DWL (nm)	Group	Flux (lm)										
														P2	67.2	XBDRED-00-0000-000000701
Red	R2	620	R3	R3	R3 63	R3	3 630	N4	62	XBDRED-00-0000-000000601						
					N3	56.8	XBDRED-00-0000-000000501									

Note: Cree maintains a tolerance of $\pm 7\%$ on flux and power measurements and ± 1 nm on dominant wavelength measurements. See the Measurements section (page 14).

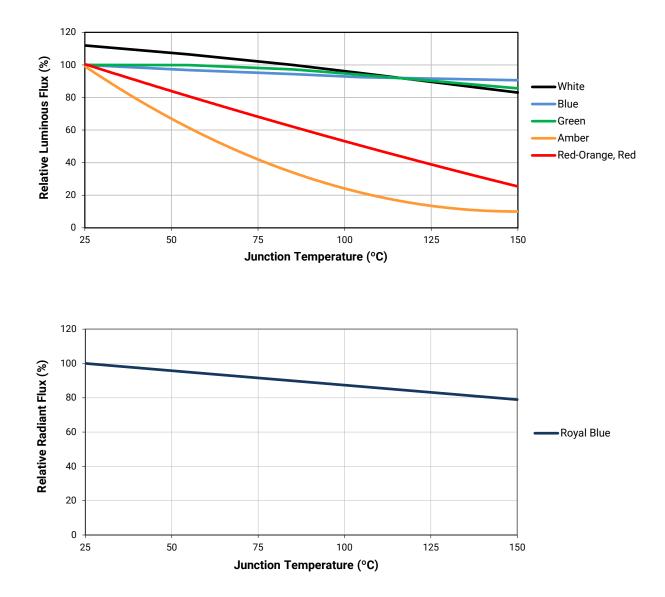
XLAMP[®] XB-D LED

RELATIVE SPECTRAL POWER DISTRIBUTION

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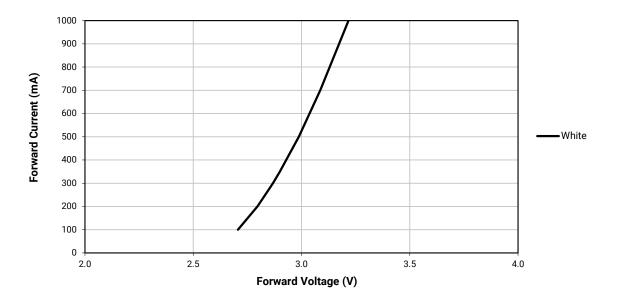


RELATIVE FLUX VS. JUNCTION TEMPERATURE ($I_F = 350 \text{ mA}$)

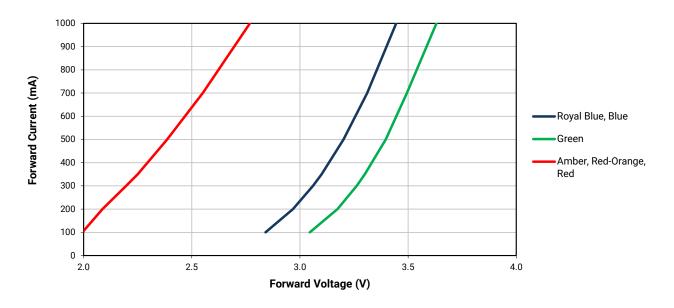


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ELECTRICAL CHARACTERISTICS ($T_J = 85 °C$)

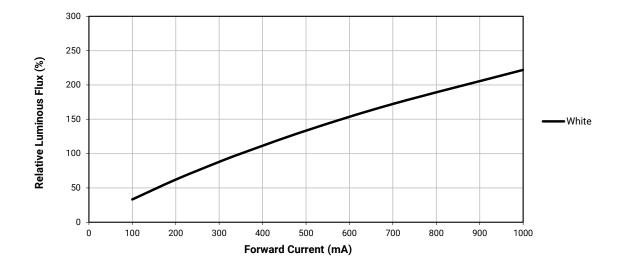


ELECTRICAL CHARACTERISTICS ($T_{J} = 25 \text{ °C}$)

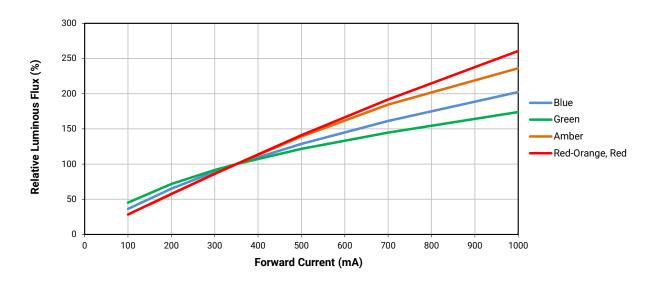


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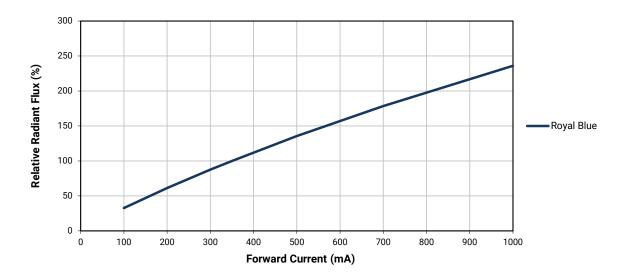
RELATIVE FLUX VS. CURRENT (T_J = 85 °C)



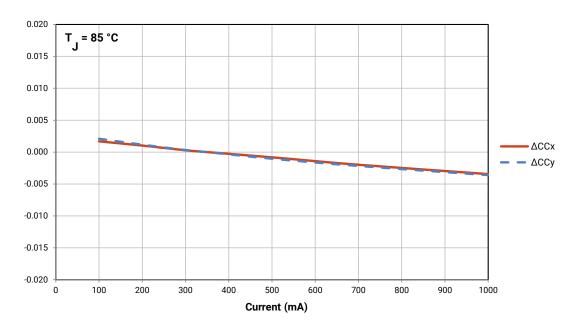
RELATIVE FLUX VS. CURRENT (T_{J} = 25 °C)



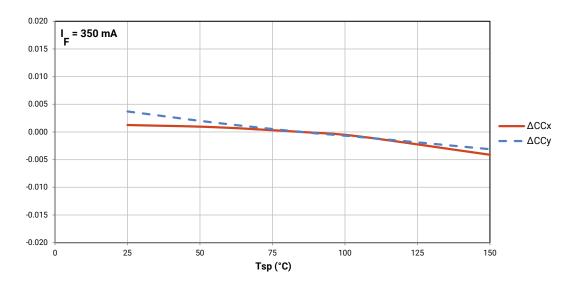
RELATIVE FLUX VS. CURRENT (T_J = 25 °C) - CONTINUED



RELATIVE CHROMATICITY VS. CURRENT (WARM WHITE)

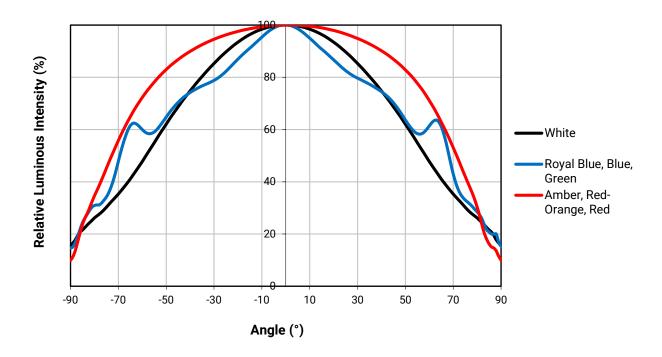






TYPICAL SPATIAL DISTRIBUTION

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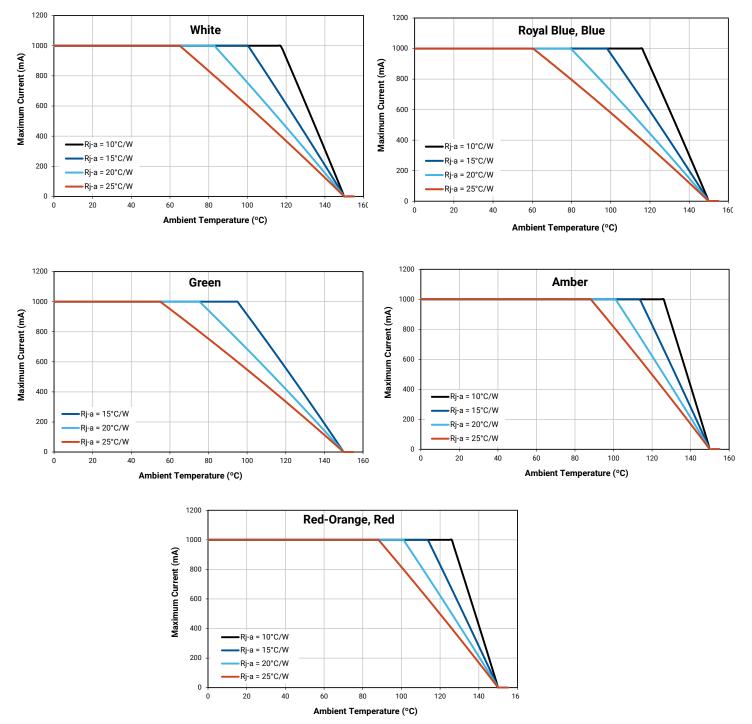
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XLAMP[®] XB-D LED



THERMAL DESIGN

The maximum forward current is determined by the thermal resistance between the LED junction and ambient. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.

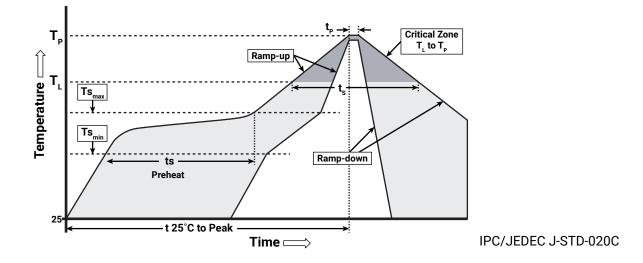


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REFLOW SOLDERING CHARACTERISTICS

In testing, Cree has found XLamp XB-D LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of the solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate (Ts _{max} to Tp)	1.2 °C/second
Preheat: Temperature Min (Ts _{min})	120 °C
Preheat: Temperature Max (Ts _{max})	170 °C
Preheat: Time (ts _{min} to ts _{max})	65-150 seconds
Time Maintained Above: Temperature (T_L)	217 °C
Time Maintained Above: Time (\boldsymbol{t}_{L})	45-90 seconds
Peak/Classification Temperature (Tp)	235 - 245 °C
Time Within 5 °C of Actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate	1 - 6 °C/second
Time 25 °C to Peak Temperature	4 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

NOTES

Measurements

The luminous flux, radiant power, chromaticity and CRI measurements in this document are binning specifications only and solely represent product measurements as of the date of shipment. These measurements will change over time based on a number of factors that are not within Cree's control and are not intended or provided as operational specifications for the products. Calculated values are provided for informational purposes only and are not intended as specifications.

Pre-Release Qualification Testing

Please read the LED Reliability Overview for details of the qualification process Cree applies to ensure long-term reliability for XLamp LEDs and details of Cree's pre-release qualification testing for XLamp LEDs.

Lumen Maintenance

Cree now uses standardized IES LM-80-08 and TM-21-11 methods for collecting long-term data and extrapolating LED lumen maintenance. For information on the specific LM-80 data sets available for this LED, refer to the public LM-80 results document.

Please read the Long-Term Lumen Maintenance application note for more details on Cree's lumen maintenance testing and forecasting. Please read the Thermal Management application note for details on how thermal design, ambient temperature, and drive current affect the LED junction temperature.

Moisture Sensitivity

Cree recommends keeping XLamp LEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain XLamp LEDs do not need special storage for moisture sensitivity.

Once the MBP is opened, XLamp XB-D LEDs may be stored as MSL 1 per JEDEC J-STD-033, meaning they have unlimited floor life in conditions of \leq 30 °C/85% relative humidity (RH). Regardless of storage condition, Cree recommends sealing any unsoldered LEDs in the original MBP.

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

REACh Compliance

REACh substances of very high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.



NOTES - CONTINUED

UL® Recognized Component

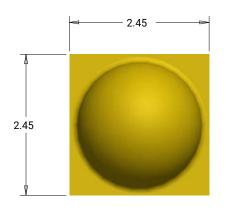
Level 4 enclosure consideration. The LED package or a portion thereof has been investigated as a fire and electrical enclosure per ANSI/ UL 8750.

Vision Advisory

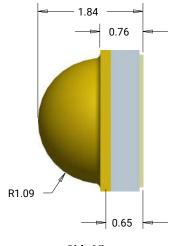
WARNING: Do not look at exposed lamp in operation. Eye injury can result. For more information about LEDs and eye safety, please refer to the LED Eye Safety application note.

MECHANICAL DIMENSIONS

Thermal vias, if present, are not shown on these drawings.

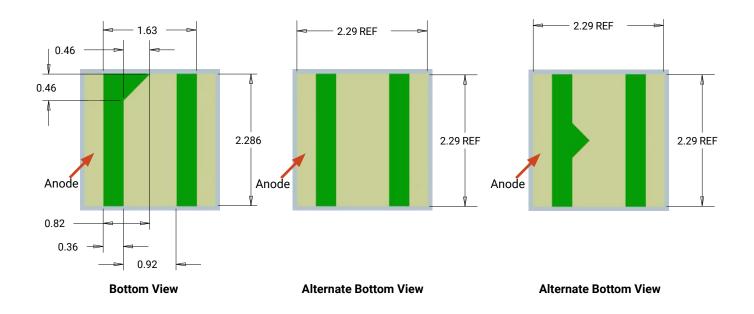




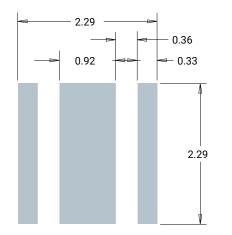


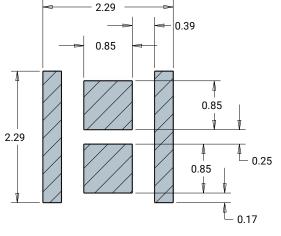
All measurements are ±.13 mm unless otherwise indicated.





MECHANICAL DIMENSIONS - CONTINUED





Recommended PCB Solder Pad

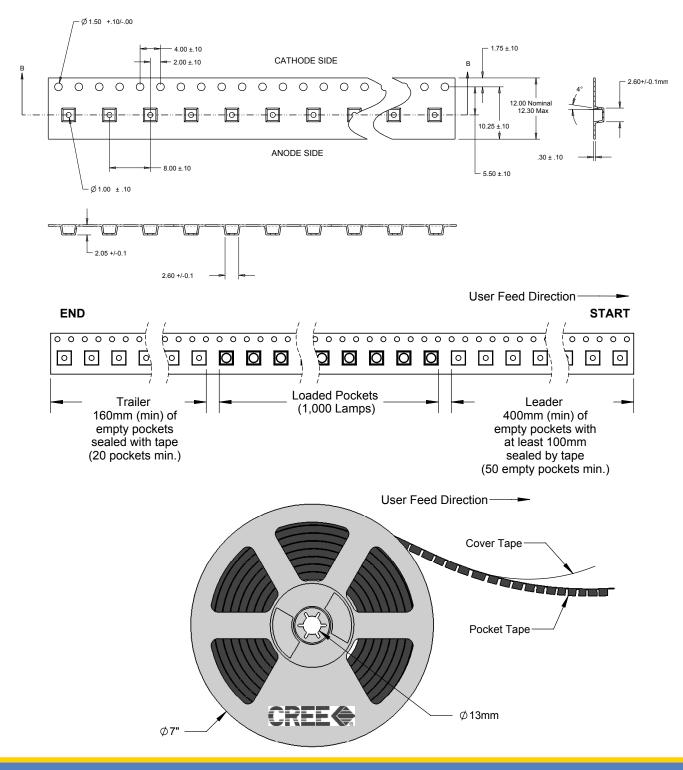
Recommended Stencil Pattern (Hatched Area is Opening)



TAPE AND REEL

All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.

Except as noted, all dimensions in mm





PACKAGING

